

HDP User Group Member Meeting with Invited Guests

Location: Embassy Suites Milpitas – Silicon Valley 901 E. Calaveras Blvd. Milpitas, CA 95035

Time: February 27th, 2008

Presentations: See HDP User Group website address: http://www.hdpug.org/6650526_38788.htm

Participants

1. Agilent, William Jones
2. Albemarle, Susan D. Landry
3. Alcatel – Lucent, Joe Smetana
4. AMD, Mike Loo
5. AMD, Eric Tosaya
6. Artesyn K.K. Chin
7. Celestica, Thilo Sack
8. Cisco, Hongtao Ma
9. Cisco, Alfred Ho
10. Cisco, Guhan Subbarayan
11. Cisco, Ken Hubbard
12. Dell, Scott O'Connell
13. Flextronics, Jennifer Nguyen
14. Fujitsu, Paul Jacovellii
15. Fujitsu, Shunichi Kikuchi
16. IBM, Jim Wilcox
17. IBM, Art Fong
18. ITRI, Dr. C.C. Hsien
19. Juniper, Michael Kluwin
20. Juniper, Chris Gross
21. Multek, Stephen J. Morris
22. Nan Ya, Andy Hicks
23. National Semiconductor, Shichun Qu
24. National Semiconductor, Stephen Gee
25. Nihon Superior, Masato Nakamura
26. Nihon Superior, Keith Howell
27. Nokia Siemens Networks, Dietmar Breisacher
28. Premier Semiconductor Services, Nick Leonardi
29. SanDisk, Naveen Kini
30. Sun Microsystems, Dave Love
31. Sun Microsystems, Bidyut Sen
32. Sun Microsystems, Mike Freda
33. Tekelec, Tony Cosentino
34. TI, Tejpal Hooghan
35. HDP User Group Ruben Bergman
36. HDP User Group, Jack Fisher
37. HDP User Group, Laurence Schultz
38. HDP User Group, Paul Collander
39. HDP User Group Marshall Andrews
40. HDP User Group Diana Miller

Agenda

1. Opening the Meeting

Marshall Andrews introduced the staff and invited guests. All participants introduced themselves

2. Presentation of New Members

Marshall Andrews introduced and welcomed the new members Chemtura, Nan Ya and Wistron

3. Project Formation/Implementation Process

Marshall Andrews reviewed the project formation and project implementation processes.

4. HDP User Group Implementation Projects Overview

The implementation projects were briefed by the present project leaders. The results of the projects will be discussed in detail at the meeting Feb 28th.

5. 09:30 Wireless Packaging

David C. Douglas, Sun Microsystems was invited to give a presentation of the SUN Microsystems wireless packaging technologies. The presentation will not be to be loaded at the website due to the nature of the contents of the presentation.

6. 10:45 HDP User Group Definition Projects

6.1 Halogen-free Product Properties Database

The project leader Scott O'Connell, Dell Computers gave the presentation.

Marshall Andrews explained the structure and function of the database system.

Dietmar Breisacher, Nokia Siemens Networks suggested that experience by users should be in the database.

A sign up sheet was circulated

6.2 Lead-free Copper Erosion

Keith Howell, Nihon Superior gave the presentation sitting in for the project leader Hideki Yamabe, Nihon Superior.

Thilo Sack, Celestica suggested that the hole fill issue should be taken into account. Jennifer Nguyen, Flextronics considered that there is no good established solution for big boards.

Dave Love asked about the test vehicle. Nihon Superior has an existing test vehicle.

Jack Fisher stated that this was a restart of the project

Dietmar Breisacher brought the equipment related effects. The experience of Nokia Siemens Networks was that it could have an impact

A sign up sheet for the project was circulated.

Jim Wilcox asked if the Nihon Superior is pre study results available to members

Action: Keith Howell shall check with the Nihon Superior Headquarter

6.3 BMPS Module to PWB Interconnections

Ruben Bergman, HDP User Group gave the presentation.

A sign up sheet for the project was circulated.

6.4 BMPS Guideline

Ruben Bergman, HDP User Group gave the presentation.

6.5 Halogen-free PCBA Reliability

Chi-Chen Hsien, ITRI gave the presentation sitting in for the project leader Tao Chih Chang, ITRI.

Marshall Andrews asked for help with the concept of a test vehicle

Scott the best would ask the suppliers about what they could deliver

A sign up sheet for the project was circulated.

6.6 Mechanical Fatigue for Solder Joint Rel Testing

Marshall Andrews HDP User Group sitting in for the project leader Hironori Ohta, NEC gave the presentation.

Marshall Andrews mentioned that the project now is in the implementation stage

6.7 SAC Aging Study

The project leader Dave Love, SUN Microsystems gave the presentation.

Dave Love mentioned that he had an agreement with Jim Wilcox about him taking over the leadership for the project

6.8 Multiple Alloy Screening

The project leader Joe Smetana, Alcatel-Lucent gave the presentation.

7 New Project Ideas

7.1 Embedded passives

Paul Collander presented a proposal for an Embedded Passive project.

Michael Kluwin, Juniper mentioned that it is not possible for Juniper to get the benefits out of the project. Hand held type devices may more fit for exploring the technology

Decision: The project idea will be put on hold until two companies are interested in actively participating in the project with resources

7.2 Extended Copper Erosion

Thilo suggested than addition to the existing Copper Erosion project

Decision: Thilo Sack and Keith Howell shall have an off line discussion about the possible outline of such a project

7.3 Hole Fill

Jennifer Nguyen, Flextronics mentioned that there are problems with getting the holes filled with solder. There are two specifications namely Telcordia GR 26 spec and IPC spec. A project may be needed

Decision: Jennifer Nguyen, Joe Smetana and Thilo Sack shall discuss a possible project about Telcordia GR 26 spec versus IPC spec

8 Visitors Assessment of Meeting

Nick Leonard, Premier was impressed by the results of the group. There is a lot of commitment by members.

9 Adjourn

The meeting was adjourned 16:00

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